

CALL FOR ABSTRACTS FOR RAMPOP CONFERENCE, NEWPORT ON 26 NOVEMBER 2026

Call for Abstracts for RF, Microwave and Photonics Packaging (RaMPoP) Conference to be held on Thursday 26th November 2026 at the Semiconductor Catapult, Newport, South Wales, NP10 8BE

Assembly and Packaging is necessary to make RF, microwave and photonics devices reliable and manufacturable products. As operating frequencies push into the mmWave band and beyond and signals cross between the electrical and optical domains, the package itself becomes a critical part of the circuit – setting the limits on electrical and optical performance, thermal management, reliability and cost. This makes assembly and packaging a natural unifying theme across RF, microwave and photonics applications.

IMAPS-UK invites abstracts covering the following topics:

- **Materials & substrates** – low-loss laminates, LTCC/HTCC ceramics, glass and organic interposers
- **Interconnects & transitions** – flip-chip vs. wire bond, low-loss RF/mmWave transitions and vertical interconnects
- **Thermal management** – heat spreading and die-attach for high-power power devices and laser sources
- **Hermeticity & reliability** – sealing, moisture control and environmental/space qualification
- **Photonic integration** – fibre alignment and attach, electro-optic co-packaging and hybrid RF-photonics assembly
- **Modelling, test & EMC** – multiphysics co-design, shielding, grounding and antenna-in-package

Please submit your Title and Abstract of up to 200 words to office@imaps.org.uk by **Friday 28th August 2026**